



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET

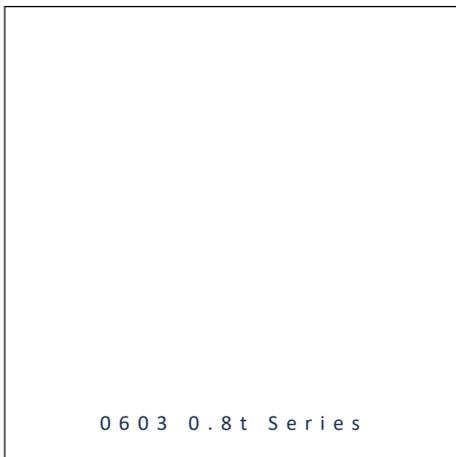


- ▶ PCB / CHIP LED
- ▶ 0603 (0.8t)
- ▶ Infrared (730nm)

NOF46S53



Release Date: 25 August 2018 Version: A1.0



0603 0.8t Series

0603 0.8t Series

**RoHS
Compliant**



FEATURES:

- **Package:** PCB / CHIP LED Top View
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 1.7V
- **Radiant Power (typ.):** 4.0mW@20mA
- **Colour:** Infrared (IR)
- **Wavelength:** 730nm
- **Viewing angle:** 140°
- **Materials:**
 - Die: AlGaAs
 - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -40~+80°C
- **Storage Temperature:** -40~+85°C
- **Grouping parameters:**
 - Forward voltage
 - Radiant intensity
 - Peak wavelength
- **Soldering methods:** Reflow
- **Preconditioning:** acc. to JEDEC Level 3
- **Packing:** 8mm tape with Max.4000/reel, ø180mm (7")

APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	50	mA
Peak Forward Current Duty 1%; Width 100μS	I _{FP}	1	A
Reverse Voltage	V _R	5	V
Reverse Current @5V	I _R	10	μA
Power Dissipation	P _D	95	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

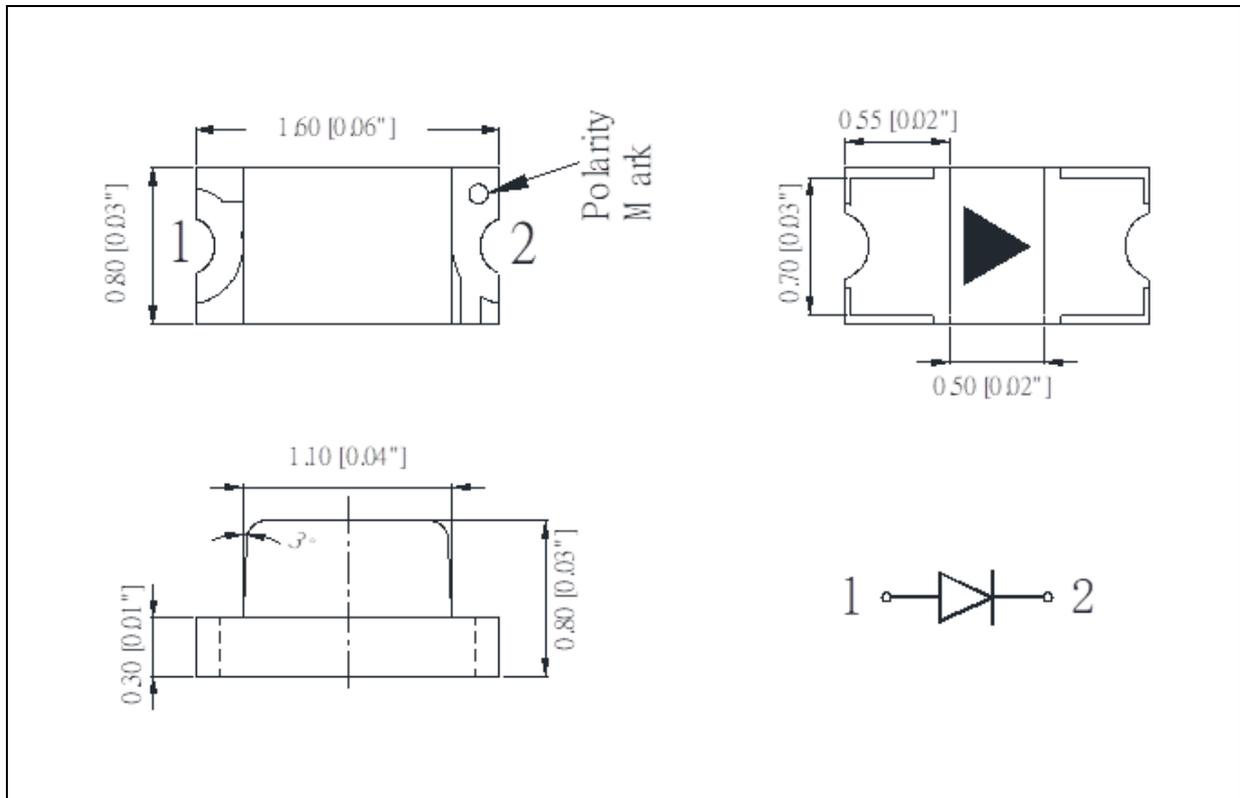
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	---	1.7	1.9	V	I _F =20mA
Radiant Power	P _O	3.2	4.0	---	mW	I _F =20mA
Peak Wavelength	λ _P	720	730	740	nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ	---	50	---	nm	I _F =20mA
Optical Rise Time	T _R	---	15	---	ns	I _F =20mA
Optical Fall Time	T _F	---	9	---	ns	I _F =20mA
Viewing Angle	2θ _{1/2}	---	140	---	deg	I _F =20mA

1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2θ_{1/2}) ±5%

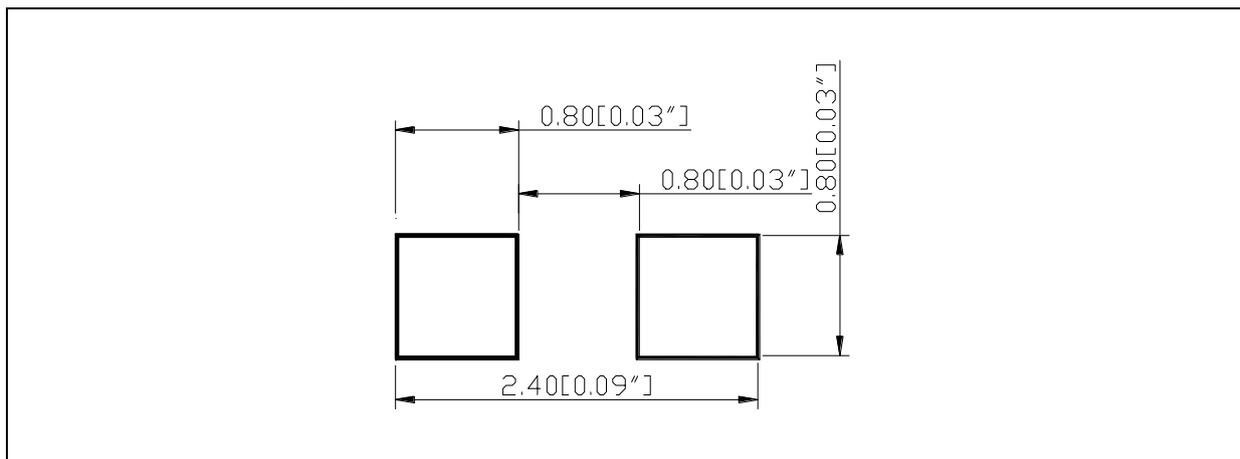
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ± 0.2 mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
V	1.5	1.9	V

 Radiant Power Classifications ($I_F = 20\text{mA}$):

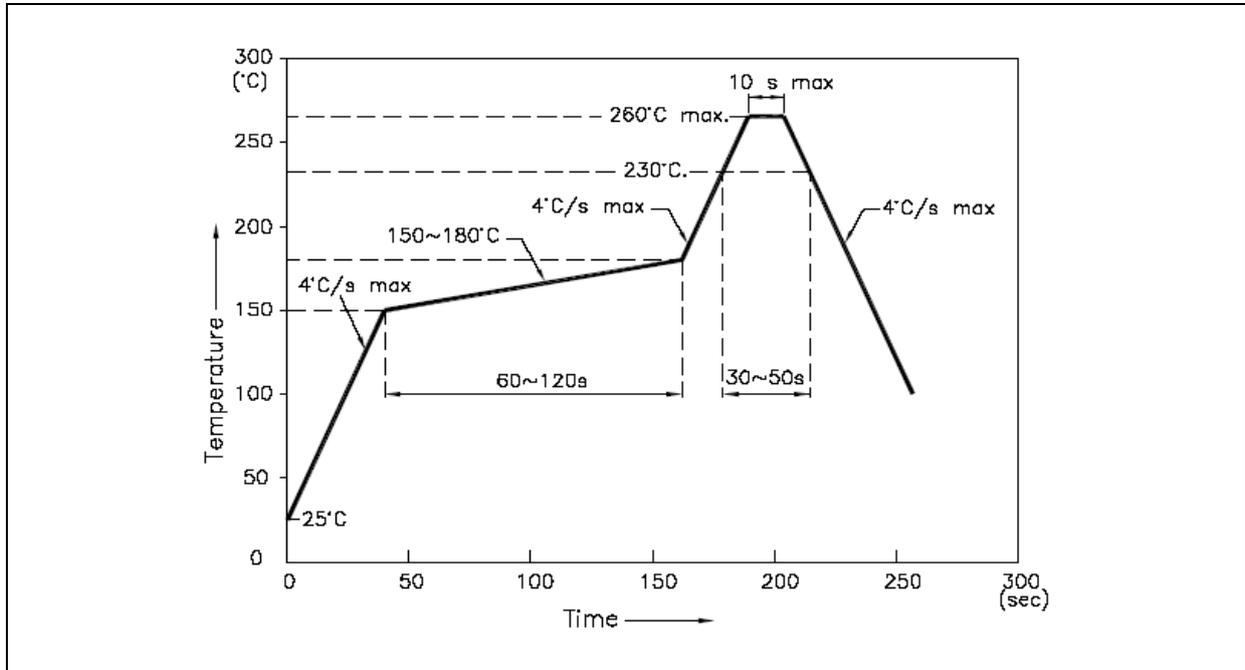
Code	Min.	Max.	Unit
A	3.2	5.4	mW

 Peak Wavelength Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
H	720	740	nm

RECOMMENDED SOLDERING PROFILE:

Reflow Solder:

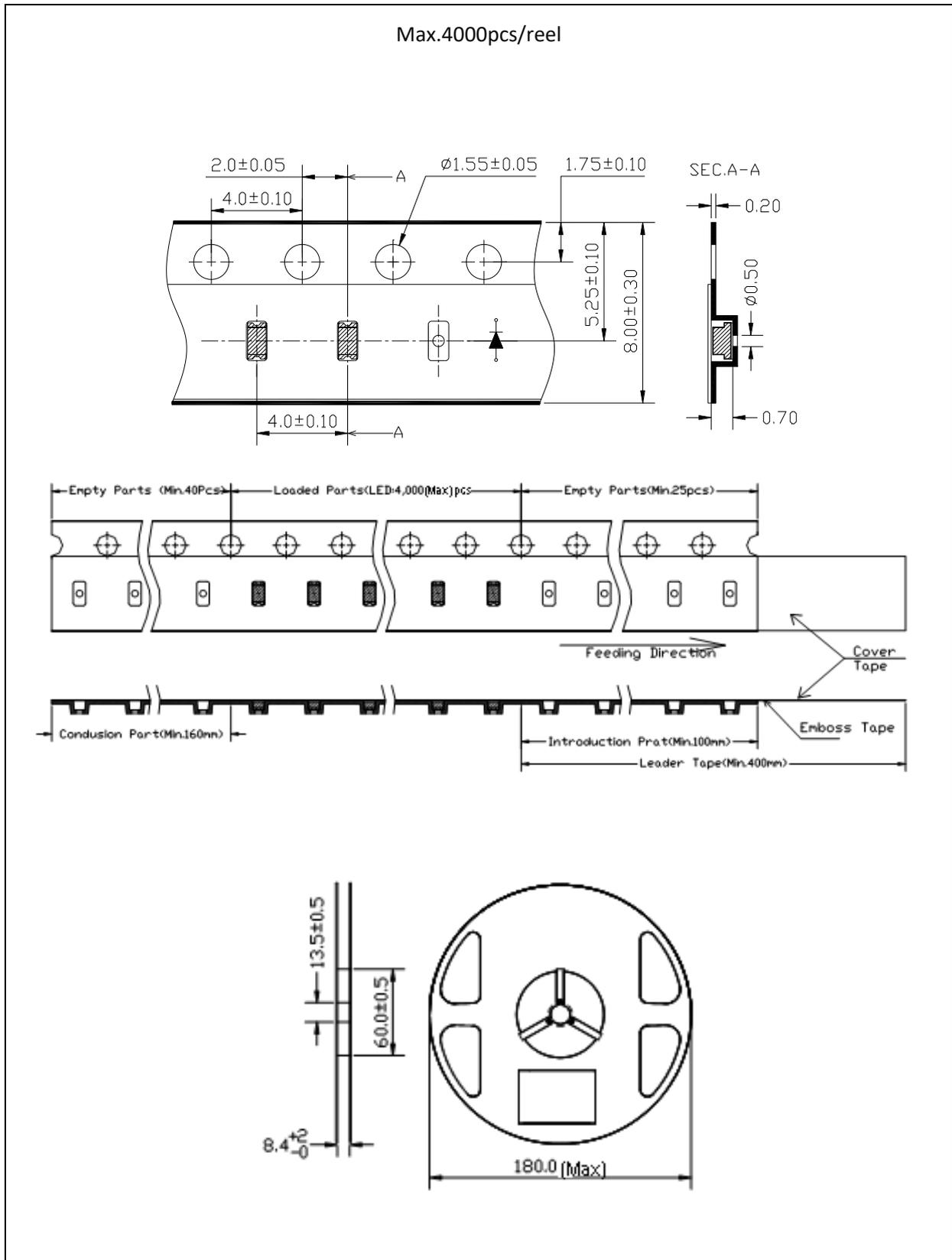


Note:

1. Recommend reflow temperature 245°C. The maximum soldering temperature should be limited to 260°C.
2. Maximum reflow soldering: 2 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent and apply baking at 60°C±5°C for 15hrs before use.

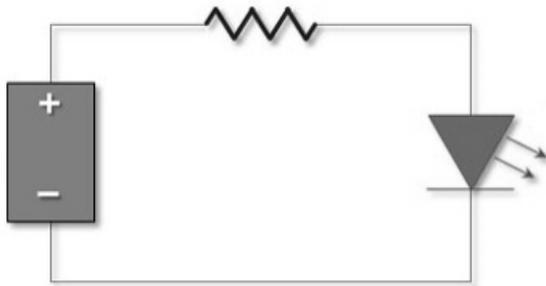
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	25/08/2018	Datasheet set-up.